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Attorney's Docket No. 042390.P5778D  
Express Mail No. EM014067311US

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of:

**Krishna Seshan; M. Lawrence A. Dass; and  
Geoffrey L. Bakker**

Serial No.

Filed: **November 6, 2001**

For: **Semiconductor Passivation Deposition  
Process for Interfacial Adhesion (Amended)**

Divisional Application of:  
Serial No. 09/105,590  
Filed: June 26, 1998

Examiner: Brophy, J.

Art Unit 2822

PRELIMINARY AMENDMENT

Box New Patent Application  
Assistant Commissioner for Patents  
Washington, D.C. 20231

Dear Sir:

In connection with the filing of the Divisional Application under Rule 1.53(b), Applicants respectfully request entry of the following amendments.

IN THE TITLE

✓  
Please change the title to --SEMICONDUCTOR PASSIVATION DEPOSITION  
PROCESS FOR INTERFACIAL ADHESION--.

IN THE SPECIFICATION

On page 1, before "Field of the Invention", please insert the following paragraph:

Cross-Reference to Related Application

A1

The application is a Divisional of co-pending application Serial No. 09/105,590, filed June 26, 1998 by applicants, Krishna Seshan, M. Lawrence A. Dass and Geoffrey L. Bakker, entitled "Semiconductor Passivation Deposition Process for Interfacial Adhesion".